

# NEWS RELEASE

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## Indium Corporation Wins EM Asia Innovation Award

[Indium Corporation](#), a leading materials provider for the electronics assembly market, recently earned an [Electronics Manufacturing \(EM\) Asia Innovation Award](#) for its new high-reliability Durafuse® HR alloy for solder paste at Productronica China in Shanghai.

Established in 2006, the EM Asia Innovation Award program recognizes and celebrates excellence in the Asian electronics industry, encouraging companies to achieve the highest standards and push the industry forward. The awards are based on strict criteria, including innovativeness, cost effectiveness, and technology advancement.



“We’re always honored to be recognized by industry peers for our innovative advances in materials science,” said Indium Corporation President and CEO [Ross Berntson](#). “Our dedicated team of engineers developed Durafuse® HR in close collaboration with our customers in the semiconductor and e-Mobility industries, among others, identifying inventive ways to address many of their electronics assembly needs and challenges.”

Durafuse® HR is a high-reliability solder alloy developed from the company’s Durafuse® mixed-alloy technology. Engineered to deliver enhanced thermal cycling performance and superior voiding performance without vacuum reflow, Durafuse® HR is designed specifically for the rigorous demands of automotive electronics and other high-reliability applications. It is ideal for manufacturers transitioning from SAC305, requiring only minimal process adjustments for easy implementation.

Among its key features, Durafuse® HR offers:

- Exceptional thermal cycling reliability, withstanding 3,000+ cycles at -40°C–125°C
- Reduced bottom-terminated component (BTC) voiding, even without vacuum reflow
- Superior shear strength for increased durability and reduced solder joint cracking

- Seamless compatibility with SAC305 reflow profiles and common PCB surface finishes (ImSn, OSP, ENIG)
- Optimized yield rates and reliability, reducing defects, rework, and overall production costs

To learn more about Indium Corporation's high-reliability solder technology, visit [www.indium.com](http://www.indium.com).

### **About Indium Corporation**

Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit [www.indium.com](http://www.indium.com) or email [jhuang@indium.com](mailto:jhuang@indium.com). You can also follow our experts, From One Engineer To Another® (#FOETA), at [www.linkedin.com/company/indium-corporation/](http://www.linkedin.com/company/indium-corporation/).

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*Indium Corporation Area Sales Manager Jay Zhang accepts an EM Asia Innovation Award from Messe Muenchen Shanghai Co., Ltd., Chief Financial Officer and Deputy General Manager Jan Rohde at Productronica China in Shanghai.*